

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/15/2022

Details for "SN74ALS373ADBR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN74ALS373ADBR	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	DB 20	5.3x7.2x1.95	200.8

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.107563	99.998141	999981	0.053565	536
Precious Metals	Silver	7440-22-4	0.000002	0.001859	19	0.000001	0
Sub-Total			0.107565	100	1000000	0.053566	536
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.354797	80.000045	800000	0.176686	1767
Thermoplastics	Epoxy	85954-11-6	0.088699	19.999955	200000	0.044171	442
Sub-Total			0.443496	100	1000000	0.220857	2209
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	47.658548	97.642415	976424	23.733542	237335
Copper and Its Alloys	Iron	7439-89-6	1.043892	2.138717	21387	0.519849	5198
Copper and Its Alloys	Phosphorus	7723-14-0	0.016097	0.032979	330	0.008016	80
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.014634	0.029982	300	0.007288	73
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.014634	0.029982	300	0.007288	73
Zinc and Its Alloys	Zinc	7440-66-6	0.061463	0.125925	1259	0.030608	306
Sub-Total			48.809268	100	1000000	24.306591	243066
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	4.18528	95.12	951200	2.084233	20842
Precious Metals	Gold	7440-57-5	0.03432	0.78	7800	0.017091	171
Precious Metals	Palladium	7440-05-3	0.1804	4.1	41000	0.089838	898
Sub-Total			4.4	100	1000000	2.191162	21912
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	128.124942	87.999999	880000	63.805106	638051
Other Plastics and Rubber	Carbon Black	1333-86-4	0.43679	0.3	3000	0.217518	2175
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.800781	0.55	5500	0.398782	3988
Thermoplastics	Epoxy	85954-11-6	16.234013	11.15	111500	8.084397	80844
Sub-Total			145.596526	100	1000000	72.505803	725058
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.449868	100	1000000	0.722022	7220
Sub-Total			1.449868	100	1000000	0.722022	7220
Total			200.806723			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.